



Application of Hyperspectral Imaging for Nondestructive Measurement

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Message from the Guest Editor

Dear Colleagues,

Hyperspectral imaging technology has recently emerged as a powerful analytical technique that uses vibrational spectroscopy for nondestructive quality measurement of various materials. The previously described spectroscopic analytical methods (Vis/NIR, MIR, Fluorescence, Raman spectroscopies, etc.) are well-established, non-invasive analytical techniques for the analysis of materials. However, these techniques are point-based scanning techniques and only examine a relatively small area of a specimen. Sample analysis is also more convenient and fast compared with the hyperspectral imaging technique, instead of the single sampling technique used by the other spectroscopic methods. Furthermore, HSI has instrumental flexibility and can be used to collect hyperspectral data for specimens with different sizes and shapes. With these advantages and flexibility, hyperspectral imaging has been successfully adopted in a variety of research and industry environments. This Special Issue focuses on the latest research and development of hyperspectral imaging in nondestructive measurement applications.

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Guest Editor





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